

500mW Hermetically Sealed Glass Fast Switching Diodes

FEATURES

- Small hermetically sealed glass SMD package

High switching speed: Max. 4 ns
Continuous reverse voltage: Max. 75V
Repetitive peak reverse voltage: Max. 75V
Repetitive peak forward current: Max. 450 mA







D.

MECHANICAL DATA

- Polarity: Indicated by black cathode band

Hermetically Sealed Glass

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)				
PARAMETER	SYMBOL	VALUE	UNIT	
Repetitive Peak Reverse Voltage	V_{RRM}	75	V	
Continuous Reverse Voltage	V_R	75	V	
Continuous Forward Current Fig. 2, (Note 1)	l _F	200	mA	
Repetitive Peak Forward Current	I _{FRM}	450	mA	
Non-Repetitive Peak Forward Surge Current				
Square Wave : T _J =25°C Prior to Surge : See Fig. 4				
t=1µs	I_{FSM}	4	Α	
t=1ms		1		
t=1s		0.5		
Total Power Dissipation T _{amb} =25°C, (Note 1)	P _{tot}	500	mW	
Operating Junction Temperature	T _J	200	°C	
Storage Temperature Range	T _{STG}	-65 to 200	°C	

PARAM	SYMBOL	MIN	MAX	UNIT	
Forward Voltage	See Fig. 3 I _F =10mA	V _F	-	1.0	V
Reverse Leakage Current	V _R =20V See Fig. 5	,	-	25.0	nA
	$V_R=20V$ $T_j=150$ °C	I _R	-	50.0	μA
Junction Capacitance	V _R =0 f=1.0MHz	C _J	-	4.0	pF
Reverse Recovery Time	(Note 2)	t _{rr}	-	4.0	ns
Forward Recovery Voltage	I ₌ =50 mA tr=20ns	V_{fr}	-	2.5	V

Note 1 : Device mounted on an FR4 printed-circuit board

Note 2 : Reverse recovery test conditions : I_F =10mA, I_R =60mA, R_L =100 Ω , I_{RR} =1m A



RATINGS AND CHARACTERISTICS CURVES

 $(T_A=25^{\circ}C \text{ unless otherwise noted})$

Fig. 1 Maximum Permissible Continuous Forward Current As A Function of Ambient Temperature

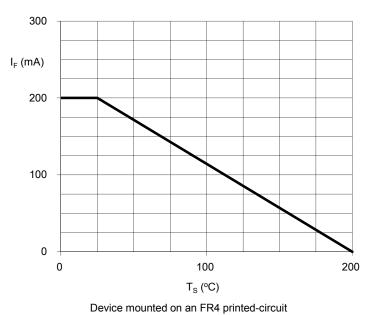
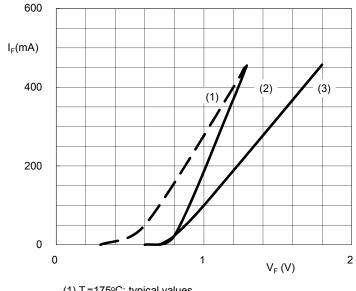


Fig. 2 Forward Current As A Function of Forward Voltage



(1) T_j=175°C; typical values (2) Tj=25°C; typical values (3) Tj=25°C; maximum values



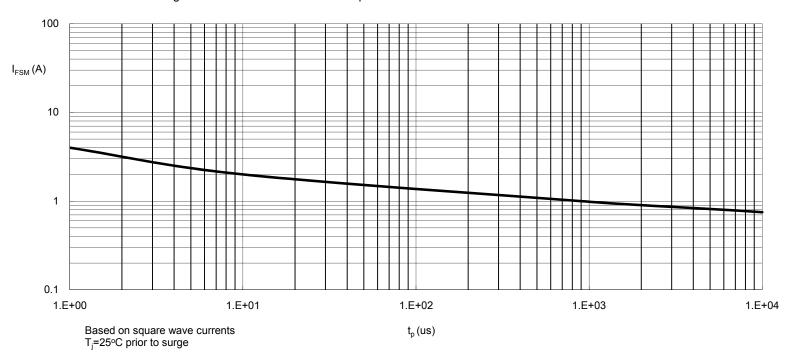
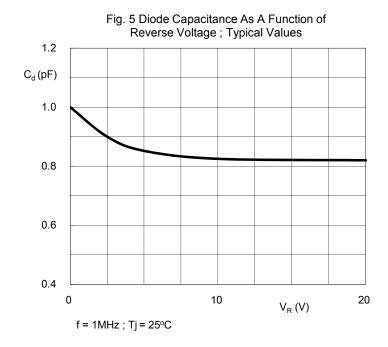


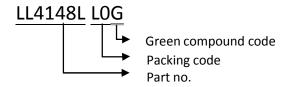


Fig. 4 Reverse Current As A Function of Junction Temperature $\begin{matrix} 1000 \\ I_R \ (uA) \end{matrix}$ $\begin{matrix} 100 \\ 100 \\ 0 \end{matrix}$ $\begin{matrix} 100 \end{matrix}$ $\begin{matrix} 100 \end{matrix}$ $\begin{matrix} 100$

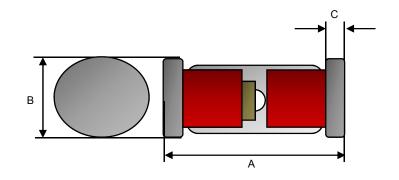




ORDER INFORMATION (EXAMPLE)

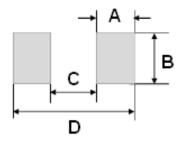


PACKAGE OUTLINE DIMENSION



DIM.	Unit (mm)		Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	3.30	3.70	0.130	0.146	
В	1.40	1.60	0.055	0.063	
С	0.20	0.50	0.008	0.020	

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)
DIIVI.	Тур.	Тур.
Α	1.25	0.049
В	2.00	0.079
С	2.50	0.098
D	5.00	0.197







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